

AMENDMENT TO THE CLAIMS

1. (ORIGINAL) A light-emitting diode for large current driving, comprising:

a metal substrate provided with a distribution circuit formed on the surface thereof and electrically insulated therefrom;

a metal base directly attached to and thereby in thermally contact with said metal substrate, and provided with an LED chip mounted thereon;

a gold wire connecting said distribution circuit with said LED chip; and

a plastic lens attached over a surface of said metal substrate on which a surface said LED chip is mounted, said lens covering part of said metal base including at least said gold wire.

2. (ORIGINAL) The light-emitting diode for large current driving according to claim 1, wherein a first through hole is formed in said metal substrate at least at one spot of which a location is corresponding to that of said plastic lens and said plastic lens is attached through said first through hole.

3. (CURRENTLY AMENDED) The light-emitting diode for large current driving according to claim 1~~or 2~~, wherein said metal base is attached to said metal substrate by means of caulking or press fitting.

4. (CURRENTLY AMENDED) The light-emitting diode for large current driving according to claim ~~any one of claims 1 to 3~~, wherein said metal base is composed of copper.

5. (CURRENTLY AMENDED) The light-emitting diode for large current driving according to claim ~~any one of claims 1 to 4~~, wherein said metal substrate is composed of copper or aluminum.

6. (CURRENTLY AMENDED) The light-emitting diode for large current driving according to claim ~~any one of claims 1 to 5~~, wherein a space is formed on a rear of said plastic lens and between said plastic lens and said metal substrate to contain said LED chip, said gold wire and part of said metal base, and is filled with a silicone resin.

7. (ORIGINAL) The light-emitting diode for large current driving according to claim 6, wherein at least one through hole is formed at a location in said metal substrate which a location corresponds to that of said space, and said silicone fills said space through said through hole.

8. (NEW) The light-emitting diode for large current driving according to claim 2, wherein said metal base is attached to said metal substrate by means of caulking or press fitting.

9. (NEW) The light-emitting diode for large current driving according to claim 2, wherein said metal base is composed of copper.

10. (NEW) The light-emitting diode for large current driving according to claim 3, wherein said metal base is composed of copper.

11. (NEW) The light-emitting diode for large current driving according to claim 2, wherein said metal substrate is composed of copper or aluminum.

12. (NEW) The light-emitting diode for large current driving according to claim 3, wherein said metal substrate is composed of copper or aluminum.

13. (NEW) The light-emitting diode for large current driving according to claim 4, wherein said metal substrate is composed of copper or aluminum.

14. (NEW) The light-emitting diode for large current driving according to claim 2, wherein a space is formed on a rear of said plastic lens and between said plastic lens and said metal substrate to contain said LED chip, said gold wire and part of said metal base, and is filled with a silicone resin.

15. (NEW) The light-emitting diode for large current driving according to claim 3, wherein a space is formed on a rear of said plastic lens and between said plastic lens and said metal substrate to contain said LED chip, said gold wire and part of said metal base, and is filled with a silicone resin.

16. (NEW) The light-emitting diode for large current driving according to claim 4, wherein a space is formed on a rear of said

plastic lens and between said plastic lens and said metal substrate to contain said LED chip, said gold wire and part of said metal base, and is filled with a silicone resin.

17. (NEW) The light-emitting diode for large current driving according to claim 5, wherein a space is formed on a rear of said plastic lens and between said plastic lens and said metal substrate to contain said LED chip, said gold wire and part of said metal base, and is filled with a silicone resin.

18. (NEW) The light-emitting diode for large current driving according to claim 2, wherein:

said metal base is attached to said metal substrate by means of caulking or press fitting;

said metal base is composed of copper;

said metal substrate is composed of copper or aluminum;

a space is formed on a rear of said plastic lens and between said plastic lens and said metal substrate to contain said LED chip, said gold wire and part of said metal base, and is filled with a silicone resin.

19. (NEW) The light-emitting diode for large current driving according to claim 18, wherein at least one through hole is formed at a location in said metal substrate which a location corresponds to that of said space, and said silicone fills said space through said through hole.